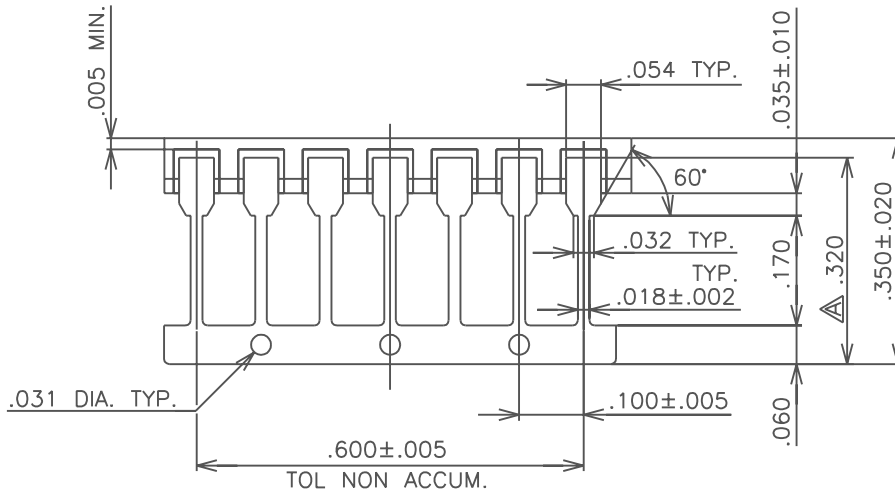
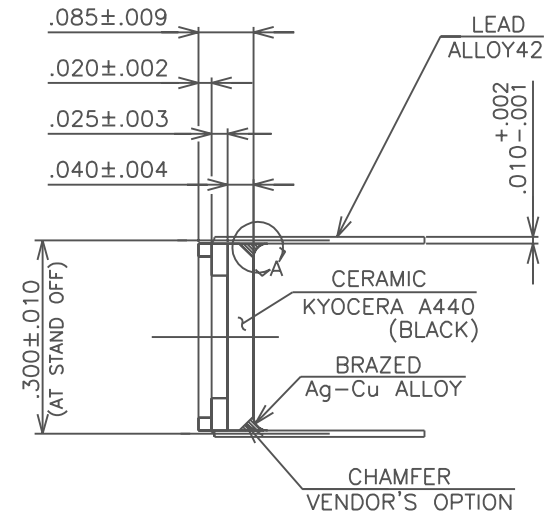
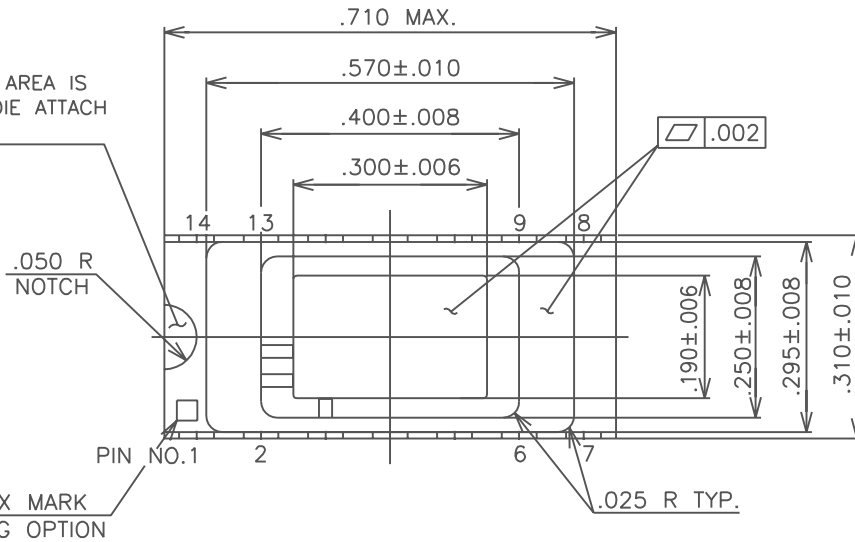


THIS METALLIZED AREA IS CONNECTED TO DIE ATTACH PAD.

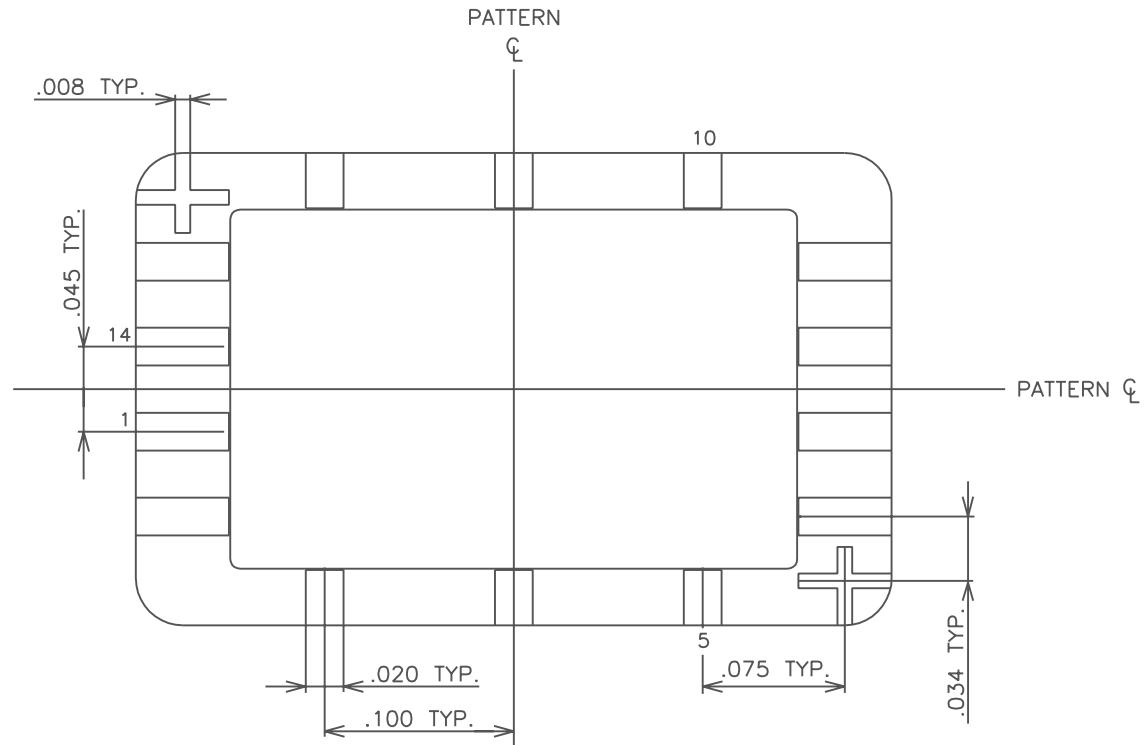


NOTES

1. GOLD PLATING 60 MICRO INCHES MIN. THICKNESS OVER 100 MICRO INCHES NOMINAL THICKNESS OF NICKEL UNLESS OTHERWISE SPECIFIED IN PURCHASE ORDER.
2. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL AREA TO BE METALLIZED.
5. LEAD RESISTANCE : 0.2 OHM MAX.

| | | | | | | | | | | | |
|--------------|---|--|------------|---------|----------|-----------------------------|---------------------------------|-------------------------|---------|----------|-------------|
| MODIFICATION | | | | | | NAME | TOLERANCE | SB014M682-1 S=0 D=0 | | | |
| | | | | | | 14 LEAD SIDE BRAZED PACKAGE | UNLESS OTHERWISE SPECIFIED | DRAWN | CHECKED | APPROVED | DATE |
| | | | | | | SCALE 5 / 1 | MATERIAL AS INDICATED | N.I | K.M | | OCT.19.'82 |
| | | | | | | | ±.005 THIRD ANGLE PROJECTION | | | | |
| | △ | CORRECTED : .325 → .320 | | | | | | | | | |
| | | REDRAWN : CONVERTED CAD DATA. ADDED : SHEET 2/2. | AUG.22.'01 | T.S/H.K | S.K/S.NI | H.SA | | DRAWING NO. KD-S82682-A | | | SHEET 1 / 2 |
| | | CHANGED | DATE | DRAWN | CHECKED | APPROVED | KYOCERA CORPORATION KYOTO JAPAN | | | | |





BONDING PATTERN

| | | | | | | | | | | | |
|--------------|---------|---------------------|------------|----------|-----------|-------------------------------------|---|----------------------------|----------------------|------------------|--------------------|
| MODIFICATION | | | | | | NAME 14 LEAD SIDE BRAZED PACKAGE | TOLERANCE UNLESS OTHERWISE SPECIFIED | DRAWN T.S./H.K. | CHECKED S.K./S.NI | APPROVED H.SA | DATE AUG.22.'01 |
| | | | | | | SCALE 15 / 1 | MATERIAL | | | | |
| | △ | ADDED : THIS SHEET. | AUG.22.'01 | T.S./H.K | S.K./S.NI | H.SA | | | | | |
| | CHANGED | DATE | DRAWN | CHECKED | APPROVED | KYOCERA CORPORATION KYOTO JAPAN | THIRD ANGLE PROJECTION | DRAWING NO. KD-S82682-A | | SHEET 2/2 | |

